

# SD103AWS/BWS/CWS

Rev.E Mar.-2016

## 描述 / Descriptions

SOD-323 塑封封装 肖特基二极管。  
Schottky Diode in a SOD-323 Plastic Package.

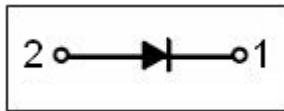
## 特征 / Features

低正向压降，可忽略的反向恢复时间。  
Low positive pressure drop, can ignore the reverse recovery time.

## 用途 / Applications

肖特基二极管。  
Schottky diode.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1:Cathode      PIN2:Anode

## 放大及印章代码 / h<sub>FE</sub> Classifications & Marking

Model	SD103AWS	SD103BWS	SD103CWS
Marking	HS4	HS5	HS6

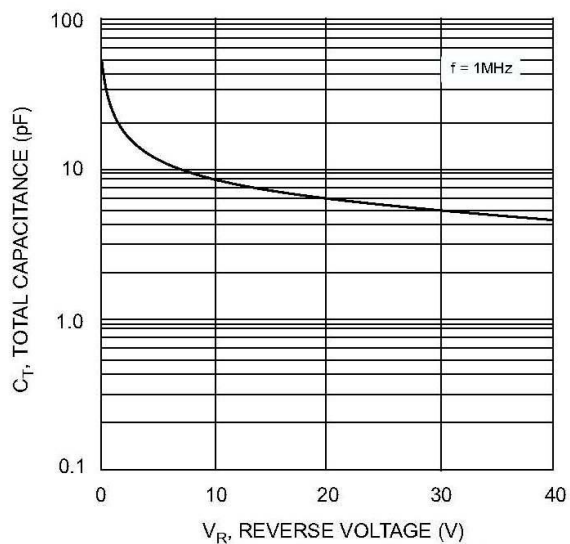
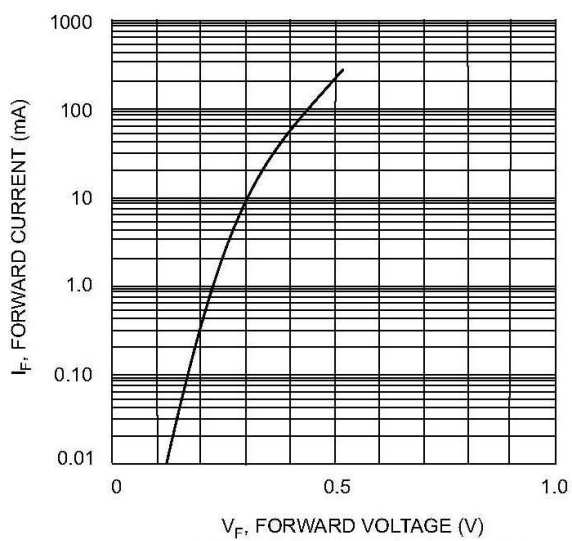
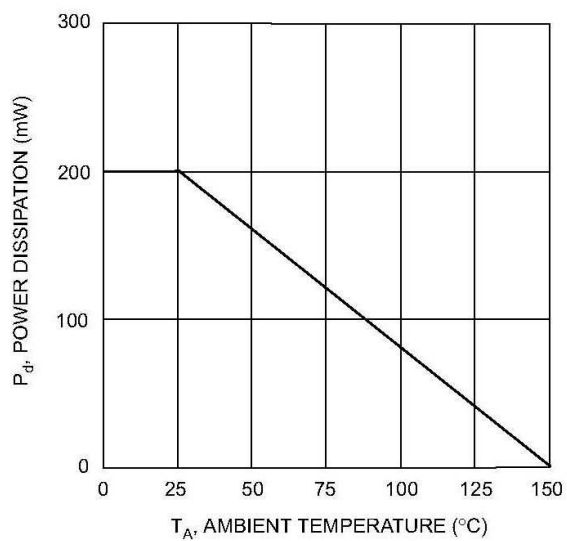
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating			单位 Unit
		SD103AWS	SD103BWS	SD103CWS	
Peak Repetitive Reverse Voltage , Working Peak Reverse Voltage DC Reverse Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	40	30	20	V
RMS Reverse Voltage	$V_{R(RMS)}$	28	21	14	V
Non-Repetitive Peak Forward Current	$I_{FM}$	350			mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}$	1.5			A
Power Dissipation	$P_D$	200			mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	625			°C/W
Junction and Storage Temperature Range	$T_J, T_{stg}$	-65~125			°C

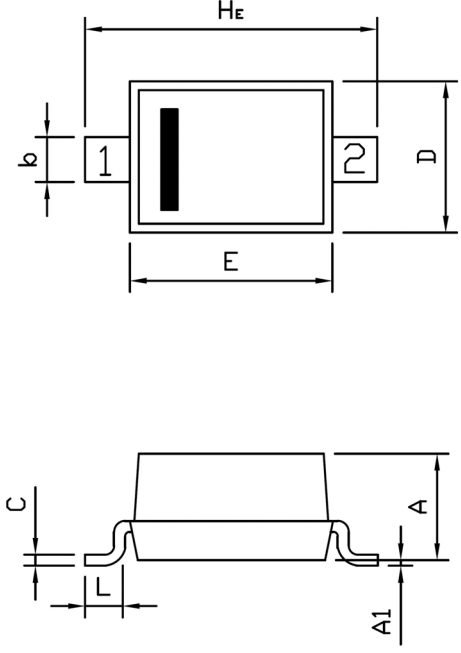
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating		单位 Unit
			MIN	MAX	
Reverse Breakdown Voltage	$V_{(BR)}$	$I_R=10\mu A$	VR		V
Forward Voltage Drop	$V_{FM}$	$I_F=20mA$		0.37	V
		$I_F=200mA$		0.6	
Instantaneous Reverse Current	$I_{RM}$	$V_R=30V$ SD103AWS		5.0	uA
		$V_R=20V$ SD103BWS			
		$V_R=10V$ SD103CWS			
Reverse Recovery Time	$t_{rr}$	$I_F=I_R=200mA$ $I_{rr}=0.1 \times I_R$ $R_L=100\Omega$	50		ns
Total Capacitance	$C_T$	$V_R=0V$ $f=1.0MHz$	10		pF

## 电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



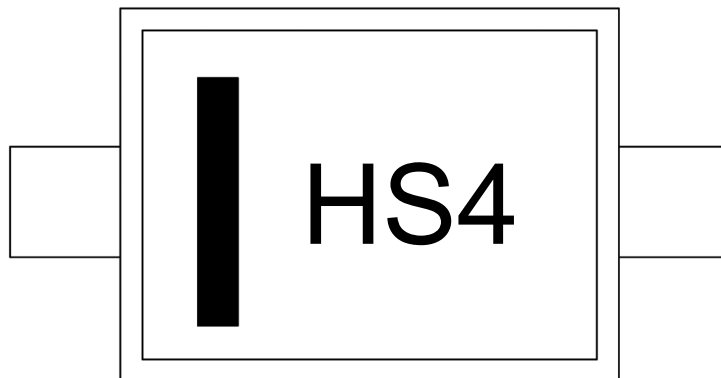
Unit: mm

尺寸 符号	SOD-323	
	min	max
A	0.90	1.10
A1	0.00	0.10
b	0.25	0.40
C	0.089	0.177
D	1.15	1.35
E	1.60	1.80
HE	2.30	2.70
L	0.20	0.40

PIN: 1.CATHODE 2.ANODE

SOD-323

印章说明 / Marking Instructions



说明：

H： 为公司代码

S4： 为型号代码

Note:

H: Company Code.

S4: Product Type.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25~150℃，时间 60~90sec;
- 2、峰值温度 245±5℃，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10℃/sec.

Note:

- 1.Preheating:25~150℃, Time:60~90sec.
- 2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5℃      时间：10±1 sec.      Temp.:260±5℃      Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	8	240,000	7" ×8	180×120×180	385×257×392

**使用说明 / Notices**